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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	384
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxbb3d6f31c6n

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Symbol	Description	V _{CCIO} (V)	Value	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/ ^o C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.35	0.200	
		1.25	0.200	
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on left/right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN} (DC)	DC current per I/O pin	300	μA
I _{IOPIN} (AC)	AC current per I/O pin	8 ⁽¹⁰⁾	mA
I _{XCVR-TX} (DC)	DC current per transceiver transmitter (TX) pin	100	mA

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-125	1.19	1.25	1.31	0.18	⁽¹⁵⁾	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

Differential HSTL and HSUL I/O Standards

Table 1-18: Differential HSTL and HSUL I/O Standards for Arria V Devices

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	$V_{CCIO} + 0.3$	—	$0.5 \times V_{CCIO}$	—	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.3	$V_{CCIO} + 0.48$
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5 \times V_{CCIO} - 0.12$	$0.5 \times V_{CCIO}$	$0.5 \times V_{CCIO} + 0.12$	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.44	0.44

Differential I/O Standard Specifications

Table 1-19: Differential I/O Standard Specifications for Arria V Devices

Differential inputs are powered by V_{CCPD} which requires 2.5 V.

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Minimum differential eye opening at the receiver serial input pins ⁽³⁰⁾	—	100	—	—	100	—	—	mV
V _{ICM} (AC coupled)	—	—	0.7/0.75/ 0.8 ⁽³¹⁾	—	—	0.7/0.75/ 0.8 ⁽³¹⁾	—	mV
V _{ICM} (DC coupled)	≤ 3.2Gbps ⁽³²⁾	670	700	730	670	700	730	mV
Differential on-chip termination resistors	85-Ω setting	—	85	—	—	85	—	Ω
	100-Ω setting	—	100	—	—	100	—	Ω
	120-Ω setting	—	120	—	—	120	—	Ω
	150-Ω setting	—	150	—	—	150	—	Ω
t _{LTR} ⁽³³⁾	—	—	—	10	—	—	10	μs
t _{LTD} ⁽³⁴⁾	—	4	—	—	4	—	—	μs
t _{LTD_manual} ⁽³⁵⁾	—	4	—	—	4	—	—	μs
t _{LTR_LTD_manual} ⁽³⁶⁾	—	15	—	—	15	—	—	μs
Programmable ppm detector ⁽³⁷⁾	—	±62.5, 100, 125, 200, 250, 300, 500, and 1000						ppm

⁽³⁰⁾ The differential eye opening specification at the receiver input pins assumes that you have disabled the **Receiver Equalization** feature. If you enable the **Receiver Equalization** feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

⁽³¹⁾ The AC coupled V_{ICM} = 700 mV for Arria V GX and SX in PCIe mode only. The AC coupled V_{ICM} = 750 mV for Arria V GT and ST in PCIe mode only.

⁽³²⁾ For standard protocol compliance, use AC coupling.

⁽³³⁾ t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

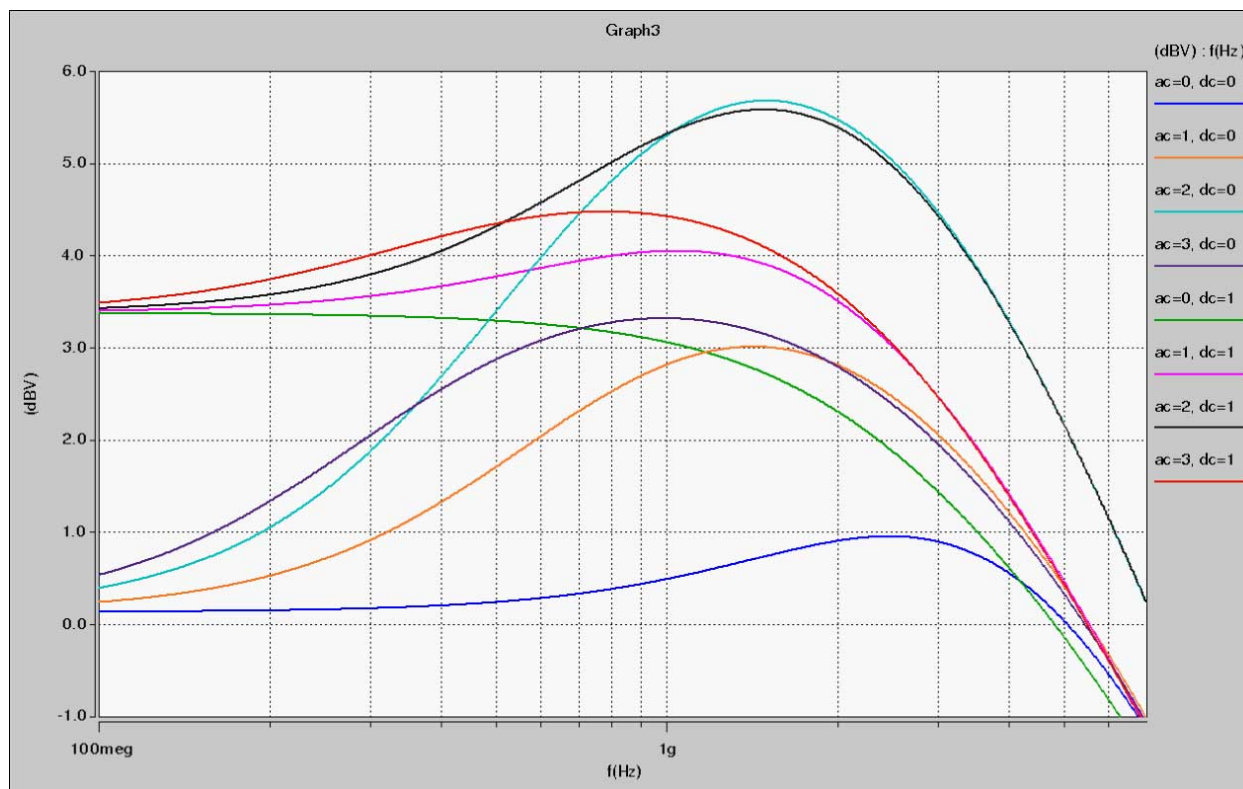
⁽³⁴⁾ t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedto data signal goes high.

⁽³⁵⁾ t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedto data signal goes high when the CDR is functioning in the manual mode.

⁽³⁶⁾ t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedto ref signal goes high when the CDR is functioning in the manual mode.

CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain

Figure 1-3: CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices



Protocol	Sub-protocol	Data Rate (Mbps)
SONET	SONET 155	155.52
	SONET 622	622.08
	SONET 2488	2,488.32
Gigabit-capable passive optical network (GPON)	GPON 155	155.52
	GPON 622	622.08
	GPON 1244	1,244.16
	GPON 2488	2,488.32
QSGMII	QSGMII 5000	5,000

Core Performance Specifications

Clock Tree Specifications

Table 1-35: Clock Tree Specifications for Arria V Devices

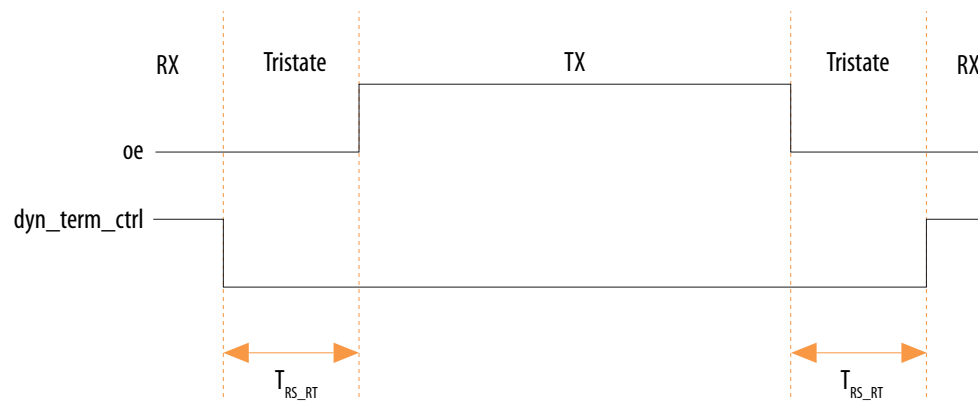
Parameter	Performance			Unit
	-I3, -C4	-I5, -C5	-C6	
Global clock and Regional clock	625	625	525	MHz
Peripheral clock	450	400	350	MHz

PLL Specifications

Table 1-36: PLL Specifications for Arria V Devices

This table lists the Arria V PLL block specifications. Arria V PLL block does not include HPS PLL.

Figure 1-7: Timing Diagram for oe and dyn_term_ctrl Signals



Duty Cycle Distortion (DCD) Specifications

Table 1-47: Worst-Case DCD on Arria V I/O Pins

The output DCD cycle only applies to the I/O buffer. It does not cover the system DCD.

Symbol	-I3, -C4		-C5, -I5		-C6		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

HPS Specifications

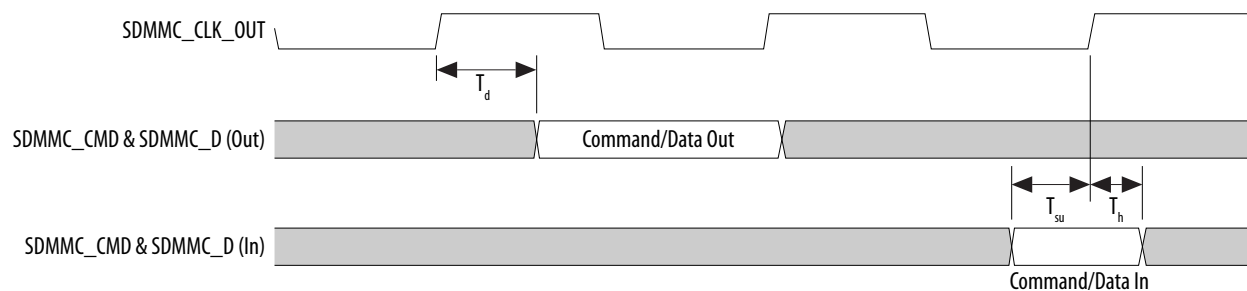
This section provides HPS specifications and timing for Arria V devices.

For HPS reset, the minimum reset pulse widths for the HPS cold and warm reset signals (HPS_nRST and HPS_nPOR) are six clock cycles of HPS_CLK1.

Symbol	Description	Min	Max	Unit
T_h	SPI MISO hold time	1	—	ns
$T_{\text{duty cycle}}$	SPI_CLK duty cycle	45	55	%
T_{dssfrst}	Output delay SPI_SS valid before first clock edge	8	—	ns
T_{dsslst}	Output delay SPI_SS valid after last clock edge	8	—	ns
T_{dio}	Master-out slave-in (MOSI) output delay	–1	1	ns

⁽⁸⁶⁾ This value is based on $\text{rx_sample_dly} = 1$ and $\text{spi_m_clk} = 120$ MHz. spi_m_clk is the internal clock that is used by SPI Master to derive its SCLK_OUT. These timings are based on rx_sample_dly of 1. This delay can be adjusted as needed to accommodate slower response times from the slave. Note that a delay of 0 is not allowed. The setup time can be used as a reference starting point. It is very crucial to do a calibration to get the correct rx_sample_dly value because each SPI slave device may have different output delay and each application board may have different path delay. For more information about rx_sample_delay , refer to the SPI Controller chapter in the Hard Processor System Technical Reference Manual.

Figure 1-11: SD/MMC Timing Diagram

**Related Information**

Booting and Configuration Chapter, Arria V Hard Processor System Technical Reference Manual

Provides more information about CSEL pin settings in the SD/MMC Controller CSEL Pin Settings table.

USB Timing Characteristics

PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.

Table 1-55: USB Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	USB CLK clock period	—	16.67	—	ns
T_d	CLK to USB_STP/USB_DATA[7:0] output delay	4.4	—	11	ns
T_{su}	Setup time for USB_DIR/USB_NXT/USB_DATA[7:0]	2	—	—	ns
T_h	Hold time for USB_DIR/USB_NXT/USB_DATA[7:0]	1	—	—	ns

FPP Configuration Timing when DCLK-to-DATA[] >1

Table 1-67: FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices

Use these timing parameters when you use the decompression and design security features.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μ s
t_{STATUS}	nSTATUS low pulse width	268	1506 ⁽⁹⁸⁾	μ s
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽⁹⁹⁾	μ s
$t_{CF2CK}^{(100)}$	nCONFIG high to first rising edge on DCLK	1506	—	μ s
$t_{ST2CK}^{(100)}$	nSTATUS high to first rising edge of DCLK	2	—	μ s
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	$N - 1/f_{DCLK}^{(101)}$	—	s
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP $\times 8/ \times 16$)	—	125	MHz
t_R	Input rise time	—	40	ns
t_F	Input fall time	—	40	ns
t_{CD2UM}	CONF_DONE high to user mode ⁽¹⁰²⁾	175	437	μ s

⁽⁹⁸⁾ This value can be obtained if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽⁹⁹⁾ This value can be obtained if you do not delay configuration by externally holding nSTATUS low.

⁽¹⁰⁰⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

⁽¹⁰¹⁾ N is the DCLK-to-DATA[] ratio and f_{DCLK} is the DCLK frequency of the system.

⁽¹⁰²⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Term	Definition
JTAG timing specifications	JTAG Timing Specifications The diagram illustrates the timing relationships between JTAG signals TMS, TDI, TCK, and TDO. TMS and TDI are high during the first two clock cycles and low during the next two. TCK is a periodic clock signal. TDO is high during the first two clock cycles and low during the next two. Various timing parameters are labeled: t_{JCP} (TCK high pulse width), t_{JCH} (TCK high setup time), t_{JCL} (TCK high hold time), t_{JPSU} (TCK high setup time to TDO), t_{JPH} (TCK high hold time to TDO), t_{JPZX} (TDO high setup time), t_{JPCO} (TDO high hold time), and t_{JPXZ} (TDO high hold time).

Term	Definition
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—Clock boost factor

Document Revision History

Date	Version	Changes
December 2016	2016.12.09	- Updated V_{ICM} (AC coupled) specifications in Receiver Specifications for Arria V GX and SX Devices table. - Added maximum specification for T_d in Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices table. - Updated T_{init} specifications in the following tables: - FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices - FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices - AS Timing Parameters for AS $\times 1$ and $\times 4$ Configurations in Arria V Devices - PS Timing Parameters for Arria V Devices
June 2016	2016.06.10	- Changed pin capacitance to maximum values. - Updated SPI Master Timing Requirements for Arria V Devices table. - Added T_{su} and T_h specifications. - Removed T_{dinmax} specifications. - Updated SPI Master Timing Diagram. - Updated T_{clk} spec from maximum to minimum in I²C Timing Requirements for Arria V Devices table.

Date	Version	Changes
November 2012	3.0	- Updated Table 2, Table 4, Table 9, Table 14, Table 16, Table 17, Table 20, Table 21, Table 25, Table 29, Table 36, Table 56, Table 57, and Table 60. - Removed table: Transceiver Block Jitter Specifications for Arria V Devices. - Added HPS information: - Added “HPS Specifications” section. - Added Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, and Table 50. - Added Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, Figure 16, Figure 17, Figure 18, and Figure 19. - Updated Table 3 and Table 5.
October 2012	2.4	- Updated Arria V GX $V_{CCR_GXBL/R}$, $V_{CCT_GXBL/R}$, and $V_{CCL_GXBL/R}$ minimum and maximum values, and data rate in Table 4. - Added receiver V_{ICM} (AC coupled) and V_{ICM} (DC coupled) values, and transmitter V_{OCM} (AC coupled) and V_{OCM} (DC coupled) values in Table 20 and Table 21.
August 2012	2.3	Updated the SERDES factor condition in Table 30.
July 2012	2.2	- Updated the maximum voltage for V_I (DC input voltage) in Table 1. - Updated Table 20 to include the Arria V GX -I3 speed grade. - Updated the minimum value of the fixedclk clock frequency in Table 20 and Table 21. - Updated the SERDES factor condition in Table 30. - Updated Table 50 to include the IOE programmable delay settings for the Arria V GX -I3 speed grade.
June 2012	2.1	Updated $V_{CCR_GXBL/R}$, $V_{CCT_GXBL/R}$, and $V_{CCL_GXBL/R}$ values in Table 4.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices

Symbol	Description	Condition (V)	Overshoot Duration as % @ $T_J = 100^\circ\text{C}$	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V _{CC}	Core voltage and periphery circuitry power supply ⁽¹¹⁵⁾	—	0.82	0.85	0.88	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹¹⁵⁾ The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-12 Class I, II	1.14	1.20	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	—	—	—

Table 2-18: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V GZ Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{ol} (mA)	I_{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7

Clock Network	ATX PLL			CMU PLL ⁽¹⁶¹⁾			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

Standard PCS Data Rate

Table 2-30: Standard PCS Approximate Maximum Date Rate (Gbps) for Arria V GZ Devices

The maximum data rate is also constrained by the transceiver speed grade. Refer to the “Commercial and Industrial Speed Grade Offering for Arria V GZ Devices” table for the transceiver speed grade.

Mode ⁽¹⁶⁴⁾	Transceiver Speed Grade	PMA Width	20	20	16	16	10	10	8	8
		PCS/Core Width	40	20	32	16	20	10	16	8
FIFO	2	C3, I3L core speed grade	9.9	9	7.84	7.2	5.3	4.7	4.24	3.76
	3	C4, I4 core speed grade	8.8	8.2	7.2	6.56	4.8	4.3	3.84	3.44

⁽¹⁶¹⁾ ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

⁽¹⁶⁴⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Core Performance Specifications

Clock Tree Specifications

Table 2-33: Clock Tree Performance for Arria V GZ Devices

Symbol	Performance		Unit
	C3, I3L	C4, I4	
Global and Regional Clock	650	580	MHz
Periphery Clock	500	500	MHz

PLL Specifications

Table 2-34: PLL Specifications for Arria V GZ Devices

Symbol	Parameter	Min	Typ	Max	Unit
$f_{IN}^{(167)}$	Input clock frequency (C3, I3L speed grade)	5	—	800	MHz
	Input clock frequency (C4, I4 speed grade)	5	—	650	MHz
f_{INPFD}	Input frequency to the PFD	5	—	325	MHz
f_{FINPFD}	Fractional Input clock frequency to the PFD	50	—	160	MHz
$f_{VCO}^{(168)}$	PLL VCO operating range (C3, I3L speed grade)	600	—	1600	MHz
	PLL VCO operating range (C4, I4 speed grade)	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%

⁽¹⁶⁷⁾ This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

⁽¹⁶⁸⁾ The VCO frequency reported by the Quartus II software in the **PLL Usage Summary** section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Memory	C3	C4	I3L	I4	
M20K Block	Single-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	455	400	455	400	MHz
	Simple dual-port with ECC enabled, 512×32	0	1	400	350	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512×32	0	1	500	450	500	450	MHz
	True dual port, all supported widths	0	1	650	550	500	450	MHz
	ROM, all supported widths	0	1	650	550	500	450	MHz

Temperature Sensing Diode Specifications

Table 2-37: Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°C to 100°C	±8°C	No	1 MHz, 500 kHz	< 100 ms	8 bits	8 bits

Table 2-38: External Temperature Sensing Diode Specifications for Arria V GZ Devices

Description	Min	Typ	Max	Unit
I_{bias} , diode source current	8	—	200	μA
V_{bias} , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
$f_{\text{HCLK_in}}$ (input clock frequency) True Differential I/O Standards ⁽¹⁷⁹⁾	Clock boost factor $W = 1$ to 40 ⁽¹⁸⁰⁾	5	—	625	5	—	525	MHz
$f_{\text{HCLK_in}}$ (input clock frequency) Single Ended I/O Standards	Clock boost factor $W = 1$ to 40 ⁽¹⁸⁰⁾	5	—	625	5	—	525	MHz
$f_{\text{HCLK_in}}$ (input clock frequency) Single Ended I/O Standards	Clock boost factor $W = 1$ to 40 ⁽¹⁸⁰⁾	5	—	420	5	—	420	MHz
$f_{\text{HCLK_OUT}}$ (output clock frequency)	—	5	—	625 ⁽¹⁸¹⁾	5	—	525 ⁽¹⁸¹⁾	MHz

Transmitter High-Speed I/O Specifications

Table 2-40: Transmitter High-Speed I/O Specifications for Arria V GZ Devices

When $J = 3$ to 10 , use the serializer/deserializer (SERDES) block.

When $J = 1$ or 2 , bypass the SERDES block.

⁽¹⁷⁹⁾ This only applies to DPA and soft-CDR modes.

⁽¹⁸⁰⁾ Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

⁽¹⁸¹⁾ This is achieved by using the LVDS clock network.

Table 2-62: Uncompressed .rbf Sizes for Arria V GZ Devices

Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ⁽²²³⁾
Arria V GZ	E1	137,598,880	562,208
	E3	137,598,880	562,208
	E5	213,798,880	561,760
	E7	213,798,880	561,760

Table 2-63: Minimum Configuration Time Estimation for Arria V GZ Devices

Variant	Member Code	Active Serial ⁽²²⁴⁾			Fast Passive Parallel ⁽²²⁵⁾		
		Width	DCLK (MHz)	Min Config Time (ms)	Width	DCLK (MHz)	Min Config Time (ms)
Arria V GZ	E1	4	100	344	32	100	43
	E3	4	100	344	32	100	43
	E5	4	100	534	32	100	67
	E7	4	100	534	32	100	67

Remote System Upgrades Circuitry Timing Specification

Table 2-64: Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
$t_{RU_nCONFIG}$ ⁽²²⁶⁾	250	—	ns
$t_{RU_nRSTIMER}$ ⁽²²⁷⁾	250	—	ns

⁽²²³⁾ The IOCSR .rbf size is specifically for the Configuration via Protocol (CvP) feature.

⁽²²⁴⁾ DCLK frequency of 100 MHz using external CLKUSR.

⁽²²⁵⁾ Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.